CUTTING COMPOUND

10320 **EN**

Innovative, highly abrasive polishing compound designed to remove deep scratches from paintwork. Easily removes traces of sandpaper up to P2000 and holograms. It safely restores gloss of the paintwork. Product does not contain silicones, which speeds up polishing process.

Directions for use: For use with a polishing machine and polishing pads of appropriate hardness. Remove residue with a microfiber towel.

The product is not classified as hazardous for human health and life and for the environment.

UFI: C1KW-80S1-300C-DFH2

MADE IN JAPAN



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